

# NEWS RELEASE

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## **Aries announces New CSP Optical FA Test Sockets for EMMI or Optical Sensor Applications**

*Window size and material options can be customized for specific applications*



**Bristol, Pa. June 2010** – Aries Electronics, an international manufacturer of standard, and custom interconnection products, now offers a CSP test socket with a window that optically exposes 100% of the top of the DUT (device under test) for FA (failure analysis) testing for EMMI (emission microscopy) or optical sensor applications. Traditionally, a hole in the socket lid only exposes a maximum of 85% of the top of the DUT surface.

Available with or without filters for UV, infrared and full spectrum applications, Aries' new optical FA test socket can be used for laser FA microscopy testing using EMMI and LSIM (laser signal injection microscopy) techniques. These FA techniques are efficient, non-invasive optical analysis tools used to detect and localize certain IC failures with maximum clarity and contrast. The techniques can be performed from either the front or back of the device.

The optical test socket line can accommodate many different optical window and lens materials, including quartz crystal, sapphire and clear plastic depending on operational requirements. The window on the standard socket uses a high-quality optical quartz V077 glass with a 98% transmission rate from <260 nm in the near UV through to >2,000 nm in the infrared.

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The new test socket can be matched to any existing socket footprint (from Aries or any other manufacturer), allowing an existing PCB to be used for FA testing or for combined testing requirements. The socket can accommodate IC device sizes from 0.75 mm\_ and up and with an IC pitch from 0.30 mm and higher. Please consult Aries for device sizes greater than 40 mm and for custom footprint layouts.

The standard contact system uses the patented Aries 2-piece spring probes with an estimated contact life of 500,000 cycles and an operating temperature of -55°C to +150°C (-67°F to +302°F). High-speed spring probes and conductive elastomeric Kapton interposers are available for RF applications from 1 GHz to over 40 GHz.

As with all Aries sockets, the new CSP optical test socket is available in custom materials, platings, sizes and configurations to suit specific customer applications.

Pricing is dependent on the number of device leads and the type of device pitch. Typical pricing for an optical test socket with 70 leads starts at \$815. Delivery is 20 working days.

For additional information, contact Aries Electronics Inc., 2609 Bartram Road, Bristol, Pa. 19007-6810; Tel: 215-781-9956; Fax: 215-781-9845; Email: [info@arieselec.com](mailto:info@arieselec.com); Web: <http://www.arieselec.com>, Data sheet #23023—[http://www.arieselec.com/Web\\_Data\\_Sheets/23023/23023.htm](http://www.arieselec.com/Web_Data_Sheets/23023/23023.htm), Europe Email: [europe@arieselec.com](mailto:europe@arieselec.com).

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**UPCOMING TRADESHOW:** SEMICON West – July 13-15, 2010 – San Francisco, CA – North Hall Booth 5670

**READER SERVICE INQUIRIES:** Please forward all reader service inquiries to Frank Folmsbee, Aries Electronics Inc., 2609 Bartram Road, Bristol, Pa. 19007-6810.

**EDITORS NOTE:** Headquartered in Bristol, Pa., Aries Electronics Inc. manufactures an extremely broad range of custom and standard interconnection and packaging products for electronics. Industry leading products include Zero Insertion Force (ZIF) test sockets for DIP, PGA, PLCC and SOIC devices; the "intelligent" Correct-A-Chip™ product line; adapters and connectors; several patented concepts for BGA (ball grid array) and LGA (land grid array) sockets; and an extensive array of high frequency test and burn in sockets. The company also specializes in meeting custom requirements for its customers.